

Item		Specification	Remarks
Number of Layer		1-16 layers	
Material		CEM-3,FR-4	High Tg CCL Is Available
Finish Board Thickness		0.2mm-3.20mm (8mil-126mil)	
Minimun Core Thickness		0.075mm(3mil)	
Copper Thickness		1/2 oz min; 3 oz max	
Min.Trace Width & Line Spacing		0.075mm/0.1mm(3mil/4mil)	
Min.Hole Diameter for CNC Driling		0.25mm(12mil)	
Min.Hole Diameter for Punching		0.9mm(35mil)	
Biggest Pabek Sise		700mm×510mm	
Dunebsuib Tikerabce	Hole Positon	+/-0.075mm(3mil) CNC Driling	
	Conductor Width(W)	+/-0.05mm(2mil)or	
		+/-20% of original artwork	
	Hole Diameter(H)	PTH L:+/-0.075mm(3mil)	
		Non-PTH L:+/-0.05mm(2mil)	
	Outline Tolerance	+/-0.125mm(5mil) CNC Routing	
		+/-0.15mm(6mil) by Punching	
Warp & Twist	0.7%		
Insulation Resistance		< 50ohm	
Test Voltage		300V	
V-Cutting	Panel Size	110×100mm(min)	Jump Score Is Available
		660×600mm(max)	
Multilayers	Layer-layer misregistration	4 layers:0.15mm(6mil)max	
		6 layers:0.25mm(10mil)max	
	Min.spacing between hole edge to circuitry pqattern of an inner layer	0.25mm(10mil)	
	Min.spacing between board oulineto circuitry pattern of an inner layer	0.25mm(10mil)	
	Board thickness tolerance	4 layers:+/-0.13mm(5mil)	
		6 layers:+/-0.15mm(6mil)	
	Impedance Control	20-75 ohm+/-10%	
Different Impedance	75-150 ohm+/-10%		
Finish Board Surface		HASL,OSP,Au /agimmersion,Au Plating Etc	